

EV Group brings high-speed, high-precision metrology to 3D heterogeneous integration – November 16, 2021

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DRAM buyers cautious about placing significant orders; opting instead to keep inventory in check. **More>>**

EV Group brings high-speed, high-precision metrology to 3D heterogeneous integration

EV Group unveiled the EVG 40 NT2 automated metrology system, which provides overlay and critical dimension (CD) measurements for wafer-to-wafer (W2W), die-to-wafer (D2W) and die-to-die (D2D) bonding as well as maskless lithography applications. **More>>**

Stanford professors to be honored for excellence in semiconductor research The Semiconductor Industry Association (SIA) and the Semiconductor Research Corporation (SRC) announced two Stanford University professors are the 2021 recipients of SIA-SRC University Research Awards: Dr. Subhasish Mitra, Professor of Electrical Engineering and of Computer Science, and Dr. Boris Murmann, Professor of Electrical Engineering. **More>>**

The 2022 IEEE Symposium on VLSI Technology Circuits announces Call for Workshop submissions

The 2022 IEEE Symposium on VLSI Technology & Circuits has announced a Call for Workshop topics in support of the conference theme: "Technology & Circuits for the Critical Infrastructure of the Future." **More>>**



Tech News

Powerful new semiconductor tool introduced by Park Systems combines atomic force microscopy with white light interferometry

Park Systems, a manufacturer of Atomic Force Microscopes, presents Park NX-Hybrid WLI, the first fully integrated system that combines Atomic Force Microscopy (AFM) with White Light Interferometer (WLI) profilometry. **More>>**

Researchers observe Marcus inverted region of charge transfer from low dimensional semiconductor materials

A research group led by Prof. WU Kaifeng from the Dalian Institute of Chemical Physics (DICP) of the Chinese Academy of Science (CAS) observed the Marcus inverted region of charge transfer from low-dimensional semiconductor materials. **More>>**

aveni, SA secures patent for groundbreaking, one-step 3D NAND wet deposition process that replaces ALD and CVD technologies

aveni SA announced that it has secured a patent that can extend the industry standard of layers from 100 to 200+ layers on a single wafer for 3D NAND memory devices. **More>>**

New ultra-high material efficient, low-cost solar cells -- using nanowires

A research group at the Norwegian University of Science and Technology (NTNU) has developed a method for making an ultra-high material efficient solar cell using semiconductor nanowires. **More>>**



Business News

Classiq to collaborate with the Fraunhofer Institute

Classiq, which provides a breakthrough Quantum Algorithm Design platform, announced that it is collaborating with the Fraunhofer Institute, an applied research organization in Europe, as well as other major academic centers, on the development of software for industrial use of quantum computers. **More>>**

JSR closes deal to acquire Inpria Corporation

JSR announced that it completed the acquisition of Corvallis, OR-based Inpria Corporation on Oct. 29, making it a wholly owned subsidiary of JSR. **More>>**

Gallium Semi selects Nijmegen, Netherlands for European R&D center Gallium Semiconductor launches its European research and development (R&D) center in Nijmegen, Netherlands. **More>>**



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